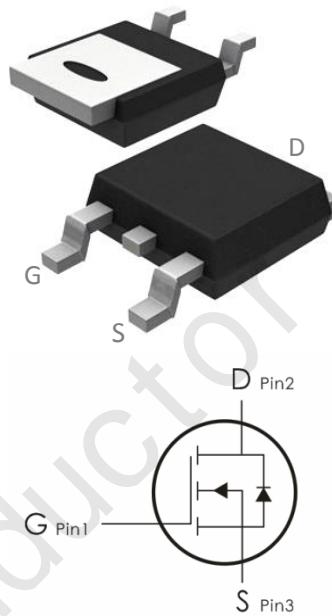


Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.



Features:

- 1) $V_{DS}=100V, I_D=15A, R_{DS(ON)}<100\text{ m}\Omega @ V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra $R_{DS(ON)}$.
- 5) Excellent package for good heat dissipation.

Absolute Maximum Ratings: ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current- $T_c=25^\circ\text{C}$	15	A
	Continuous Drain Current- $T_c=70^\circ\text{C}$	12	
	Pulsed Drain Current ¹	60	
E_{AS}	Single Pulse Avalanche Energy	16	mJ
P_D	Power Dissipation, $T_c=25^\circ\text{C}$	50	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics:

Symbol	Parameter	Max	Units
R_{eJC}	Thermal Resistance,Junction to Case	3	$^\circ\text{C}/\text{W}$
R_{eJA}	Thermal Resistance,Junction to Ambient	---	

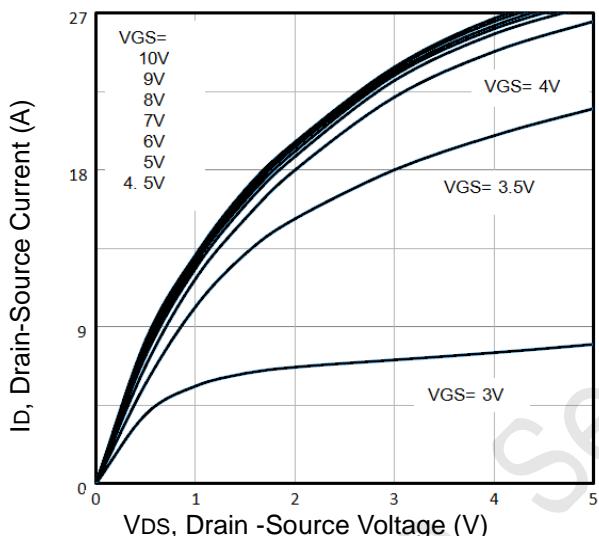
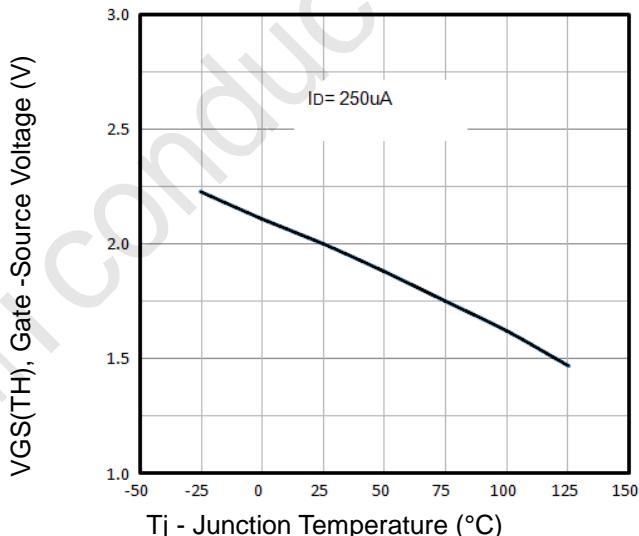
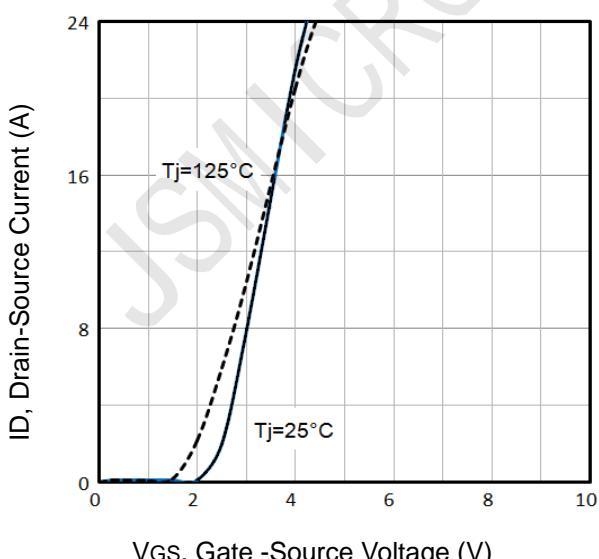
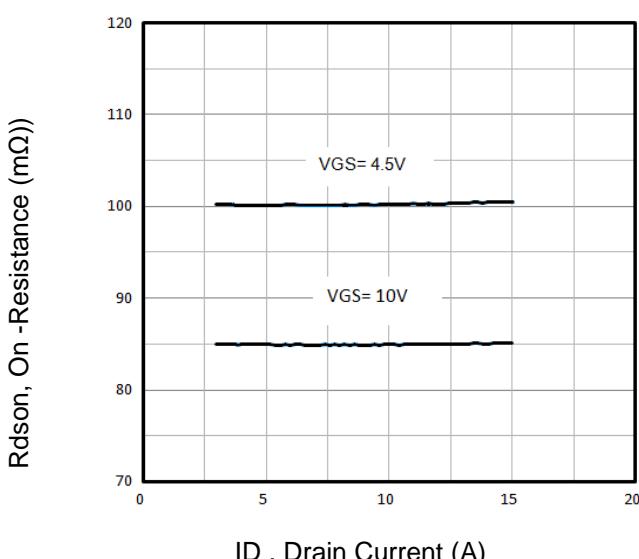
Electrical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

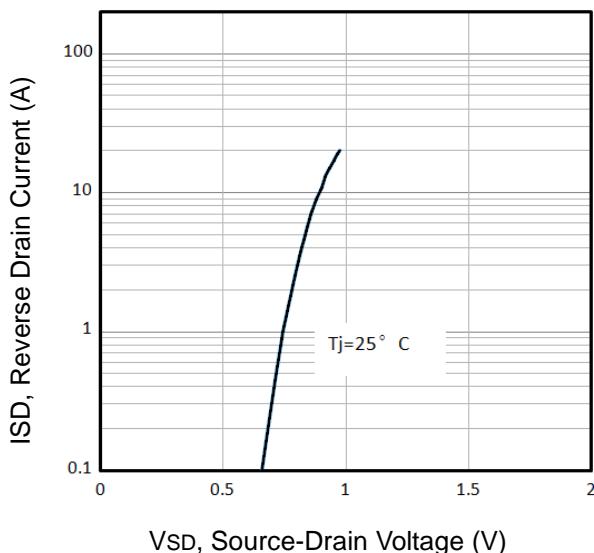
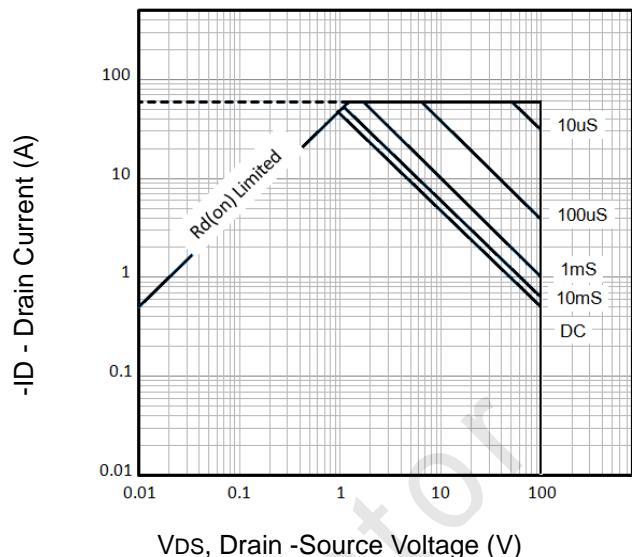
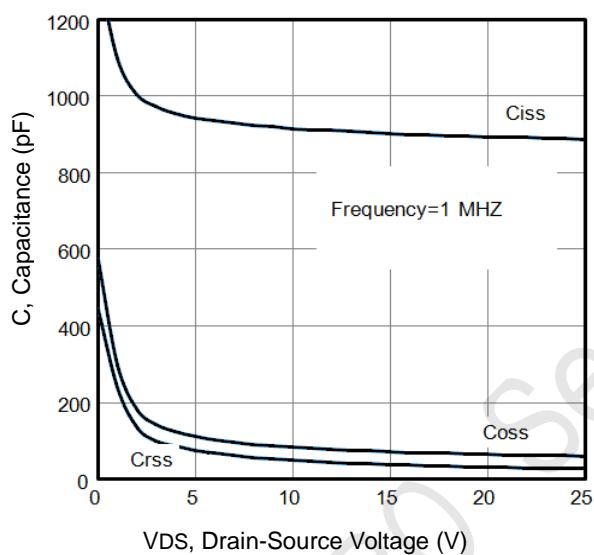
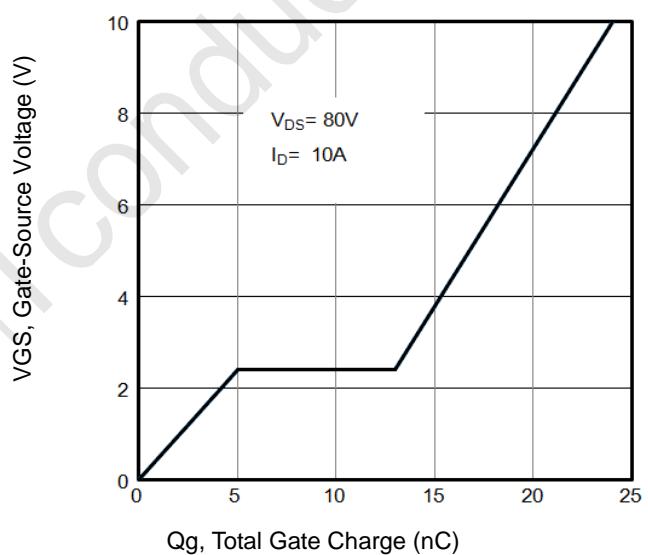
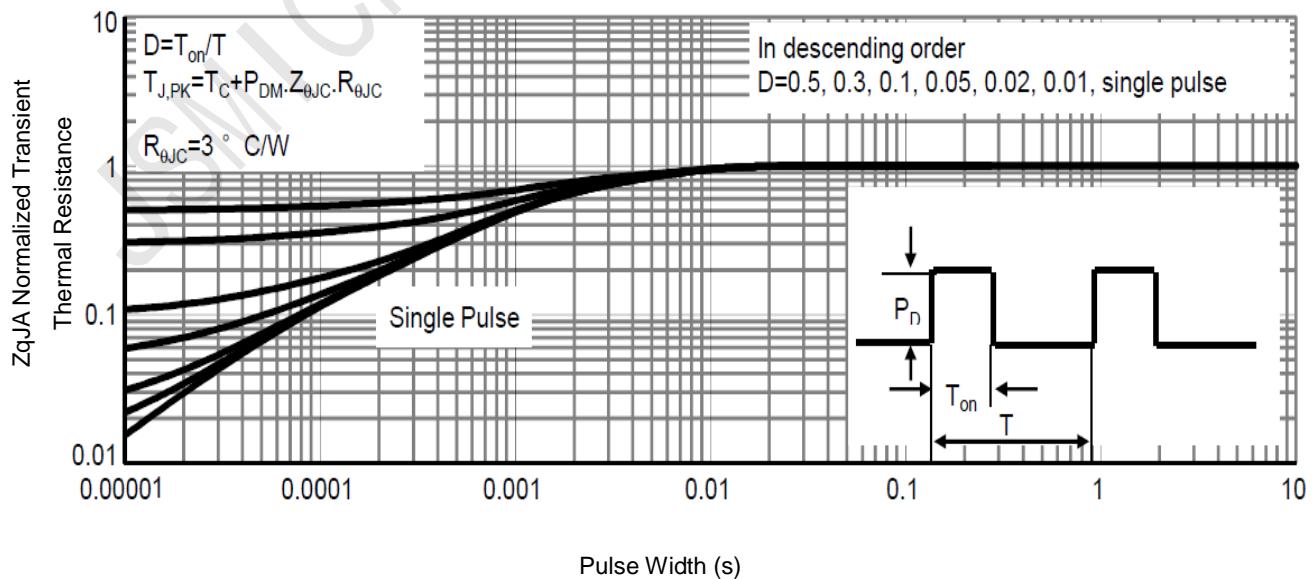
Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	100	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	± 100	nA
On Characteristics						
$V_{\text{GS(th)}}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	1	2	3	V
$R_{\text{DS(ON)}}$	Drain-Source On Resistance ³	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=10\text{A}$	---	75	100	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=8\text{A}$	---	100	115	
G_{FS}	Forward Transconductance	$V_{\text{DS}}=0\text{V}, I_{\text{D}}=0\text{A}$	---	---	---	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	890	---	pF
C_{oss}	Output Capacitance		---	60	---	
C_{rss}	Reverse Transfer Capacitance		---	25	---	
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-On Delay Time ³	$V_{\text{DD}}=25\text{V}, I_{\text{D}}=8\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=1\Omega$	---	14.2	---	ns
t_r	Rise Time ^{2,3}		---	34	---	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		---	40.4	---	ns
t_f	Fall Time ^{2,3}		---	6	---	ns
Q_g	Total Gate Charge ³	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=80\text{V}, I_{\text{D}}=10\text{A}$	---	24	---	nC
Q_{gs}	Gate-Source Charge		---	5	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	8	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage ³	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=8\text{A}$	---	0.8	1.2	V

Tr _r	Reverse Recovery Time	I _{SD} =8A, V _{GS} =0V dI/dt=100A/μs	---	35	---	Ns
q _{rr}	Reverse Recovery Charge		---	121	---	nc

Notes:

- ① Pulse width limited by maximum allowable junction temperature
- ② Limited by T_{Jmax}, starting T_J = 25°C, L = 0.1mH, R_G = 25Ω, I_{AS} = 18A, V_{GS} = 10V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycles≤ 2%.

Typical Characteristics: (T_C=25°C unless otherwise noted)

Fig1. Typical Output Characteristics

Fig2. VGS(TH) Voltage Vs. Temperature

Fig3. Typical Transfer Characteristics

Fig4. On-Resistance vs. Drain Current and Gate Voltage


Fig5. Typical Source-Drain Diode Forward Voltage

Fig6. Maximum Safe Operating Area

Fig7. Typical Capacitance Vs. Drain-Source Voltage

Fig8. Typical Gate Charge Vs. Gate-Source Voltage

Fig9. Normalized Maximum Transient Thermal Impedance

外形尺寸图 / Package Dimensions

